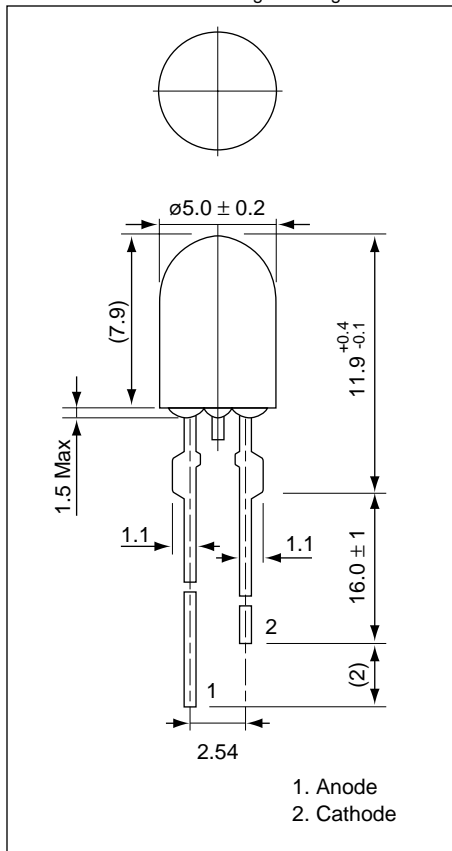


Weight: 0.35 g      Unit: mm



**AND256GC**  
GaP Green Light Emission  
T-1 3/4 Package (5 mm)

## Features

- Peak wavelength ( $\lambda_p = 567 \text{ nm}$ ) high brightness emission
- Two chips per lamp
- Low drive current
- Standard T-1 3/4 size
- Fast response time, suitable for pulse drive
- Wide radiation pattern, specially for backlighting

### Maximum Ratings (T = 25°C)

Characteristics	Symbol	Rating	Unit
Forward Current	$I_F$	25	mA
Reverse Voltage	$V_R$	8	V
Power Dissipation	$P_D$	140	mW
Operating Temperature Range	$T_{Opr}$	-30 to 85	°C
Storage Temperature Range	$T_{Stg}$	-40 to 100	°C

### Electro-Optical Characteristics (T = 25°C)

Characteristics	Symbol	Test Condition	Minimum	Typical	Maximum	Unit
Forward Voltage	$V_F$	$I_F = 20\text{ mA}$	—	4.2	5.4	V
Reverse Current	$I_R$	$V_R = 4\text{ V}$	—	—	5	$\mu\text{A}$
Luminous Intensity	$I_V$	$I_F = 20\text{ mA}$	32	90	—	mcd
Peak Emission Wavelength	$\lambda_P$	$I_F = 20\text{ mA}$	—	567	—	nm
Spectral Line Half Width	$\Delta\lambda$	$I_F = 20\text{ mA}$	—	25	—	nm
Dominant Wavelength	$\lambda_d$	$I_F = 20\text{ mA}$	—	563	—	nm
Full Viewing Angle	$\theta$	$I_V = 1/2\text{ Peak}$	—	90	—	degree

### Precaution

Please be careful of the following:

1. Soldering temperature: 260°C max  
Soldering time: 3 sec. max  
Soldering portion of lead: up to 2 mm from the body of the device
2. The lead can be formed up to 5 mm from the body of the device without forming stress.  
Soldering should be performed after the lead forming.

